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| FORM 1473<br>DEPARTMENT OF COMMERCE<br>PATENT AND TRADEMARK OFFICE  |   | DOCKET                          | APPLICATION NO |       |          |                            |                          |
|---|---|---------------------------------|----------------|-------|----------|----------------------------|--------------------------|
|   |   | 08/19451-SVA/P3 EICH SILICON JB | 09/507,629     |       |          |                            |                          |
| INFORMATION DISCLOSURE STATEMENT<br>IN AN APPLICATION<br><small>(use several sheets if necessary)</small>   |   | APPLICANT: SHEN et al.          |                |       |          |                            |                          |
|   |   | FILING DATE                     | GROUP ART UNIT |       |          |                            |                          |
|   |   | 02/18/2000                      | 1746 1763      |       |          |                            |                          |
| <b>U.S. PATENT DOCUMENTS</b>  |   |                                 |                |       |          |                            |                          |
| EXAMINER INITIAL  | DOCUMENT NUMBER   | DATE                            | NAME           | CLASS | SUBCLASS | FILING DATE IF APPROPRIATE |                          |
| <i>JKO</i>  | 5,259,923   | 11/9/1993                       | HORI et al     |       |          |                            |                          |
| <i>JKO</i>  | 5,384,009   | 1/24/1995                       | MAK et al      |       |          |                            |                          |
| <i>JKO</i>  | 5,180,464   | 1/19/1993                       | TAISU MI et al |       |          |                            |                          |
| <i>JKO</i>  | 6,270,634   | 8/7/2001                        | KUMAR et al    |       |          |                            |                          |
| <i>JKO</i>  | 6,125,859   | 10/3/2000                       | KAO et al      |       |          |                            |                          |
| <i>JKO</i>  | 5,861,233   | 1/19/1999                       | SEKINE et al   |       |          |                            |                          |
| <b>FOREIGN PATENT DOCUMENTS</b>   |   |                                 |                |       |          |                            |                          |
| EXAMINER INITIAL  | DOCUMENT NUMBER   | DATE                            | COUNTRY        | CLASS | SUBCLASS | ABSTRACT                   |                          |
|   |   |                                 |                |       |          | YES                        | NO                       |
|   |   |                                 |                |       |          |                            |                          |
|   |   |                                 |                |       |          |                            |                          |
|   |   |                                 |                |       |          |                            |                          |
|   |   |                                 |                |       |          |                            |                          |
| <b>OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)</b>   |   |                                 |                |       |          |                            |                          |
| <i>JKO</i>  | Kamizuka, Masakatsu et al "Pattern Profile Control in Magnetron reactive ion etching of Poly-Si" J. Vac. Sci. Technol. B 10(5), Sept/Oct 1992, pp. 2192-2196. |                                 |                |       |          |                            |                          |
| EXAMINER:   |   | <i>Allan Ober</i>               |                |       |          |                            | DATE CONSIDERED: 5/24/03 |
| EXAMINER: Initial if reference considered; whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and no considered. Include copy of this form with next communication to applicant. |   |                                 |                |       |          |                            |                          |